

**SURFACE MOUNT  
SCHOTTKY BARRIER RECTIFIERS**

REVERSE VOLTAGE - **20 to 60** Volts  
FORWARD CURRENT - **3.0** Amperes

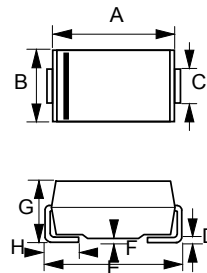
**FEATURES**

- For surface mounted applications
- Metal-Semiconductor junction with guardring
- Epitaxial construction
- Very Low forward voltage drop
- High current capability
- Plastic material has UL flammability classification 94V-0
- For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications

**MECHANICAL DATA**

- Case : Molded plastic
- Polarity : Indicated by cathode band
- Weight : 0.002 ounces, 0.064 grams

**SMA**



SMA		
DIM.	MIN.	MAX.
A	4.06	4.57
B	2.29	2.92
C	1.27	1.63
D	0.15	0.31
E	4.83	5.59
F	0.05	0.20
G	2.01	2.40
H	0.76	1.52
All Dimensions in millimeter		

**MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS**

Ratings at 25°C ambient temperature unless otherwise specified.  
Single phase, half wave, 60Hz, resistive or inductive load.  
For capacitive load, derate current by 20%

CHARACTERISTICS	SYMBOL	B320A	B330A	B340A	B350A	B360A	UNIT
Maximum Recurrent Peak Reverse Voltage	V <sub>RRM</sub>	20	30	40	50	60	V
Maximum RMS Voltage	V <sub>RMS</sub>	14	21	28	35	42	V
Maximum DC Blocking Voltage	V <sub>DC</sub>	20	30	40	50	60	V
Maximum Average Forward Rectified Current @T <sub>L</sub> = 100°C	I <sub>(AV)</sub>	3.0					A
Peak Forward Surge Current 8.3ms single half sine-wave super imposed on rated load	I <sub>FSM</sub>	100					A
Maximum forward Voltage at 3.0A DC	V <sub>F</sub>	0.5			0.7		V
Maximum DC Reverse Current at Rated DC Blocking Voltage @T <sub>J</sub> = 25°C @T <sub>J</sub> = 100°C	I <sub>R</sub>	0.5			20		mA mA
Typical Junction Capacitance (Note 1)	C <sub>J</sub>	200					pF
Typical Thermal Resistance (Note 2, 4)	R <sub>θJL</sub>	22					°C/W
Typical Thermal Resistance (Note 3, 4)	R <sub>θJA</sub>	100					°C/W
Operating Temperature Range	T <sub>J</sub>	-55 to +125			-55 to +150		°C
Storage Temperature Range	T <sub>STG</sub>	-55 to +150					°C

- NOTES : 1. Measured at 1.0MHz and applied reverse voltage of 4.0V DC.  
2. Thermal Resistance Junction to Lead.  
3. Thermal Resistance Junction to Ambient.  
4. Unit mounted on 0.75t glass-epoxy substrate with 2x3 mm copper pad.

